

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s) : Akihiko ENDO et al.

Group Art Unit: 2823

Appln. No. : 10/570,663

Examiner: Hsien Ming LEE

I.A. Filed : September 8, 2004

Confirmation No.: 1239

For : METHOD FOR PRODUCING BONDED WAFER

**AMENDMENT UNDER 37 C.F.R. § 1.111**

Commissioner for Patents  
U.S. Patent and Trademark Office  
Customer Service Window, Mail Stop Amendment  
Randolph Building  
401 Dulany Street  
Alexandria, VA 22314

Sir:

Responsive to the Office Action of October 3, 2007, reconsideration and withdrawal of the rejections made therein are respectfully requested in view of the following amendments and remarks. Inasmuch as the three-month shortened statutory period was originally set in the Office Action to expire on January 3, 2008, no extension of time or fee is believed due at this time. However, if any extension is deemed to be necessary, the same is hereby requested and the Patent and Trademark Office is authorized to charge any necessary fees to maintain the pendency of this application to Deposit Account No. 19-0089.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks/Arguments** begin on page 5 of this paper.